

2 MRT.

(19)



JAPANESE PATENT OFFICE

## PATENT ABSTRACTS OF JAPAN

(11) Publication number: 09237867 A

(43) Date of publication of application: 09.09.97

(51) Int. Cl

**H01L 25/00****H01L 23/04**

(21) Application number: 08042528

(71) Applicant: KYOCERA CORP

(22) Date of filing: 29.02.96

(72) Inventor: UCHIMURA HIROSHI  
TAKENOSHITA TAKESHI

## (54) HIGH-FREQUENCY PACKAGE

## (57) Abstract:

**PROBLEM TO BE SOLVED:** To provide a high-frequency package which is equipped with an antenna element and a high-frequency device, compact in structure, suitable for massproduction, and suitably applicable to a system of high-frequency such as microwave or millimeter wave.

**SOLUTION:** An antenna circuit board A is composed of an antenna element 3, a high-frequency line 4 which feeds an electric power to the antenna element 3, and a first dielectric board 2 where the high-frequency line 4 and the antenna element 3 are provided, and a high-frequency device circuit board B is composed of a second dielectric board 7 where a cavity 8 is provided, a high-frequency device 9 housed in the cavity 8, and a transmission line 11 which transmits signal to the high-frequency device 9, and a high-frequency package is equipped with the boards A and B, wherein the boards A and B are joined into one piece, and the high-frequency line 4 of the antenna circuit board A and the transmission line 11 of the high-frequency device circuit board B are connected together by electromagnetic coupling.

COPYRIGHT: (C)1997,JPO

